

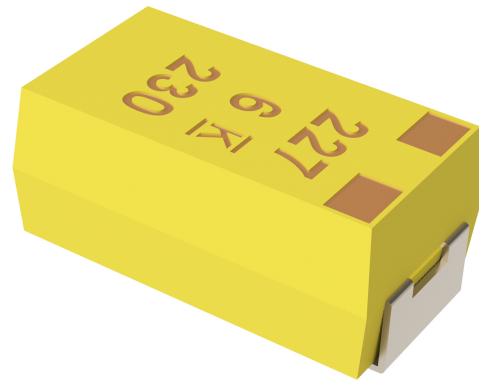
## Overview

The KEMET T490 Series, designed for customer product applications (low temperature demanding applications), meets RoHS compliance with leads constructed of 100% matte tin and green molding compound. This series is classified as MSL (Moisture Sensitivity Level) 1 under J STD 020: unlimited floor life time at  $\leq 30^{\circ}\text{C}/85\% \text{ RH}$ .

Tin/lead (Sn/Pb) terminations are available upon request for any part number. Gold-plated terminations are also available for use with conductive epoxy attachment processes. Standard packaging of these devices is tape and reel in accordance with EIA 481. This system provides perfect compatibility with all tape-fed placement units.

## Benefits

- Taped and reeled per EIA 481
- Symmetrical compliant terminations
- Optional gold-plated terminations
- Laser-marked case
- Suitable for 3 x 260°C reflow passes
- Halogen-free epoxy
- Capacitance values of 47  $\mu\text{F}$  to 470  $\mu\text{F}$
- Tolerance of  $\pm 20\%$
- Voltage rating of 4 – 10 VDC
- 0.2% per 1,000 hours at 85°C 0.5 V<sub>R</sub> Reliability
- Small and low profile case sizes
- RoHS Compliant and lead-free terminations
- MSL Reflow Temp  $\leq 260^{\circ}\text{C} = 1$
- Operating temperature range of  $-55^{\circ}\text{C}$  to  $+40^{\circ}\text{C}$



## Applications

Typical applications include decoupling and filtering in communications end applications such as cellphones and consumer mobile.

## Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.

## K-SIM

For a detailed analysis of specific part numbers, please visit [ksim.kemet.com](http://ksim.kemet.com) to access KEMET's K-SIM software. KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels.

## Ordering Information

T	490	B	227	M	006	A	T	
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Failure Rate/Design	Termination Finish	Packaging (C-Spec)
T = Tantalum	Industrial	A B T	First two digits represent significant figures. Third digit specifies number of zeros.	M = ±20%	004 = 4 006 = 6.3 010 = 10	A = N/A	T = 100% Matte Tin (Sn) plated H = Standard solder coated (SnPb 5% Pb minimum) G = Gold plated (A, B only)	Blank = 7" Reel 7280 = 13" Reel

## Performance Characteristics

Item	Performance Characteristics
Operating Temperature	-55°C to 40°C
Rated Capacitance Range	47 – 470 µF at 120 Hz/25°C
Capacitance Tolerance	M Tolerance (20%)
Rated Voltage Range	4 – 10 V
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	≤ 0.01 CV (µA) at rated voltage after 5 minutes

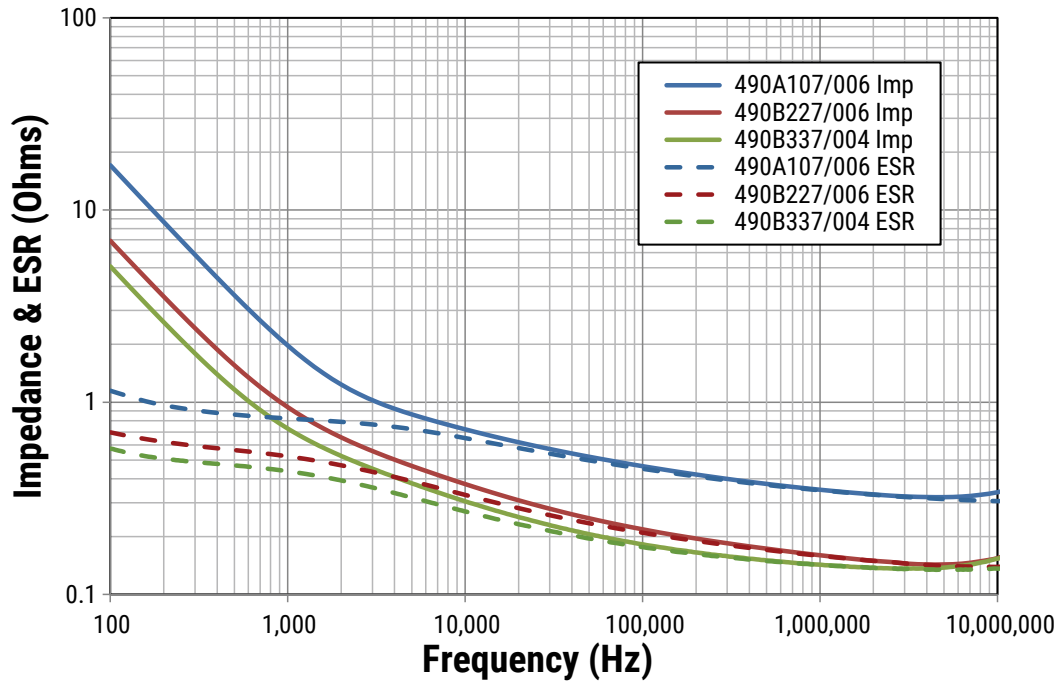
## Qualification

Test	Condition	Characteristics				
Endurance	40°C at 1.0 V <sub>R</sub> 85°C at 1/2 V <sub>R</sub> and 125°C at 1/5 rated voltage, 1,000 hours	Δ C/C	Within +10%/-20% of initial value			
		DCL	Within 2 x initial limit			
		ESR	Within 2.5 x initial limits			
Storage Life	85°C at 0 volts, 1,000 hours	Δ C/C	Within +10%/-20% of initial value			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Humidity	40°C, 93% RH, 1,000 hours, no load	Δ C/C	Within -5%/+35% of initial value			
		DCL	Within 2.0 x initial limit			
Temperature Stability	Extreme temperature exposure at a succession of continuous steps at +25°C, -55°C, +25°C, +85°C, +125°C, +25°C	+25°C	-55°C	+85°C	+125°C	
		Δ C/C	IL*	±10%	±20%	±30%
		DCL	IL	N/A	10 x IL	15 x IL
Surge Voltage	40°C, 1.32 x rated voltage 1,000 cycles	Δ C/C	Within +10%/-20% of initial value			
		DCL	Within 2.0 x initial limits			
		ESR	Within 1.25 x initial limits			

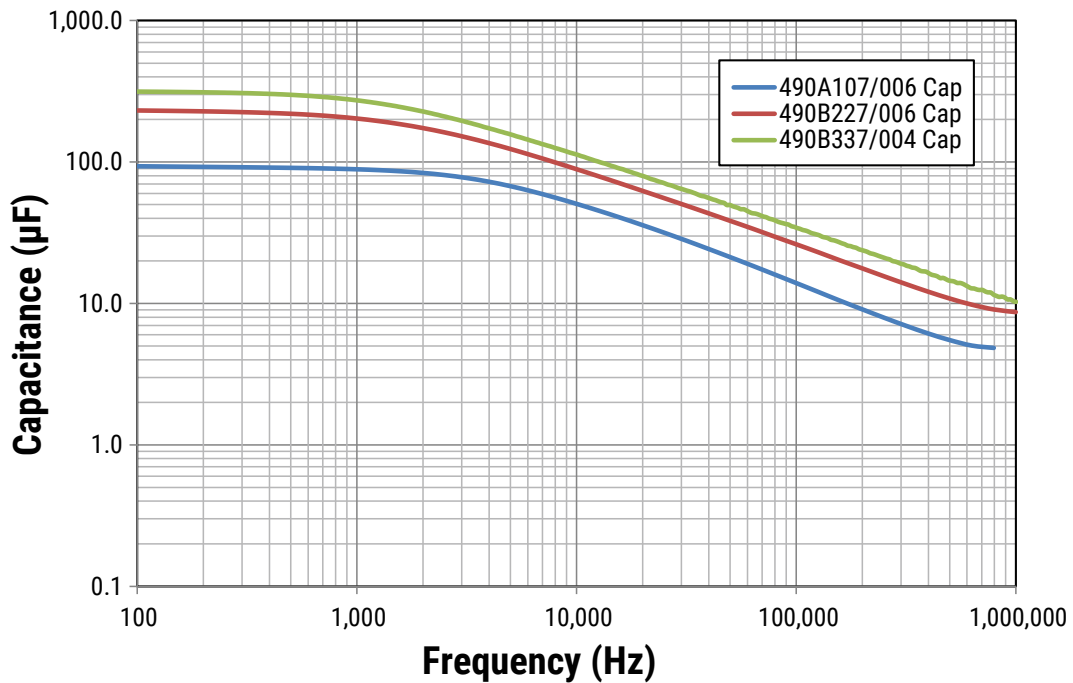
\*IL = Initial limit

## Electrical Characteristics

ESR vs. Frequency

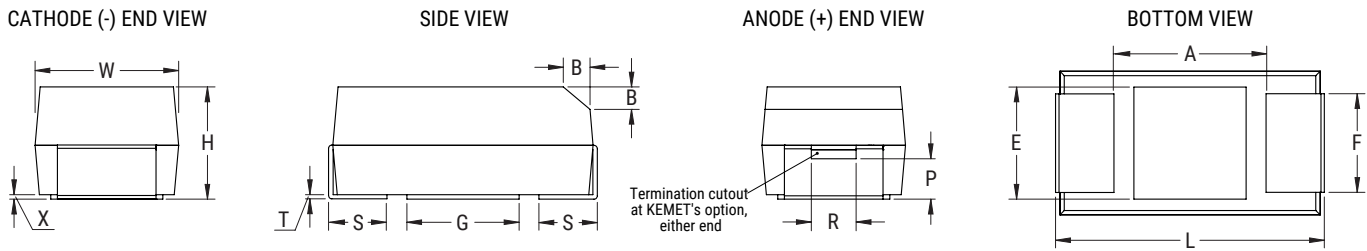


Capacitance vs. Frequency



## Dimensions – Millimeters (Inches)

Metric will govern



Case Size		Component												
KEMET	EIA	L	W	H	F ±0.1 ±(.004)	S	B ±0.15 (Ref) ±.006	X (Ref)	P (Ref)	R (Ref)	T (Ref)	A (Min)	G (Ref)	E (Ref)
A	3216-18	3.2±0.2 (0.126±0.008)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	1.2 (0.047)	0.80 (0.032) +0.2 (0.008)/-0.3 (0.011)	0.4 (.016)	0.10±0.10 (0.004±0.004)	0.4 (0.016)	0.4 (0.016)	0.13 (0.005)	1.2 (0.047)	1.1 (0.043)	1.3 (0.051)
B	3528-21	3.5±0.2 (0.138±0.008)	2.8±0.2 (0.110±0.008)	1.9±0.2 (0.075±0.008)	2.2 (0.087)	0.80 (0.032) +0.2 (0.008)/-0.3 (0.011)	0.4 (.016)	0.10±0.10 (0.004±0.004)	0.5 (0.020)	1.0 (0.039)	0.13 (0.005)	1.9 (0.075)	1.8 (0.071)	2.2 (0.087)
T	3528-12	3.5±0.2 (0.138±0.008)	2.8±0.2 (0.110±0.008)	1.2 (0.047)	2.2 (0.087)	0.80 (0.032) +0.2 (0.008)/-0.3 (0.011)	N/A	0.05 (0.002)	N/A	N/A	0.13 (0.005)	1.9 (0.075)	1.8 (0.071)	2.2 (0.087)

Notes: (Ref) – Dimensions provided for reference only. For low profile cases, no dimensions are provided for B, P or R because these cases do not have a bevel or a notch.

**Table 1 – Ratings & Part Number Reference**

Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	ESR	Maximum Allowable Ripple Current	Maximum Operating Temp	MSL
VDC at 40°C	µF	KEMET/EIA	(See below for part options)	µA at +20°C Maximum/ 5 Minutes	Ω at +20°C 100 kHz Maximum	mA at +25°C 100 kHz	°C	Reflow Temp ≤ 260 °C
4	100	A/3216-18	T490A107M004A(1)E500	4.0	0.5	387	40	1
4	150	A/3216-18	T490A157M004A(1)E800	6.0	0.8	306	40	1
4	150	T/3528-12	T490T157M004A(1)E1K1	6.0	1.1	252	40	1
4	220	B/3528-21	T490B227M004A(1)E500	8.8	0.5	412	40	1
4	330	B/3528-21	T490B337M004A(1)E800	13.2	0.8	326	40	1
4	470	B/3528-21	T490B477M004A(1)E1K0	18.8	1.0	291	40	1
6	47	T/3528-12	T490T476M006A(1)E800	2.8	0.8	295	40	1
6	68	A/3216-18	T490A686M006A(1)E1K0	4.1	1.0	274	40	1
6	68	T/3528-12	T490T686M006A(1)E600	4.1	0.6	342	40	1
6	100	A/3216-18	T490A107M006A(1)E500	6.0	0.5	387	40	1
6	100	A/3216-18	T490A107M006A(1)E800	6.0	0.8	306	40	1
6	100	T/3528-12	T490T107M006A(1)E1K0	6.0	1.0	265	40	1
6	150	B/3528-21	T490B157M006A(1)E500	9.0	0.5	412	40	1
6	150	B/3528-21	T490B157M006A(1)E800	9.0	0.8	326	40	1
6	220	B/3528-21	T490B227M006A(1)E300	13.2	0.3	532	40	1
6	220	B/3528-21	T490B227M006A(1)E500	13.2	0.5	412	40	1
6	330	B/3528-21	T490B337M006A(1)E800	19.8	0.8	326	40	1
10	47	T/3528-12	T490T476M010A(1)E1K0	4.7	1.0	265	40	1
10	47	A/3216-18	T490A476M010A(1)E1K0	4.7	1.0	274	40	1
10	150	B/3528-21	T490B157M010A(1)E500	15.0	0.5	412	40	1
10	150	B/3528-21	T490B157M010A(1)E800	15.0	0.8	326	40	1
10	220	B/3528-21	T490B227M010A(1)E800	22.0	0.8	326	40	1
VDC at 40°C	µF	KEMET/EIA	(See below for part options)	µA at +20°C Maximum/ 5 Minutes	Ω at +20°C 100 kHz Maximum	mA at +25°C 100 kHz	°C	Reflow Temp ≤ 260 °C
Rated Voltage	Rated Capacitance	Case Code/ Case Size	KEMET Part Number	DC Leakage	ESR	Maximum Allowable Ripple Current	Maximum Operating Temp	MSL

(1) To complete KEMET part number, insert T = 100% Matte Tin (Sn) Plated, G = Gold Plated, H = Standard Solder coated (SnPb 5% Pb minimum). Designates termination finish.

**Blue color text denotes "Under Development"**

Refer to Ordering Information for additional detail.

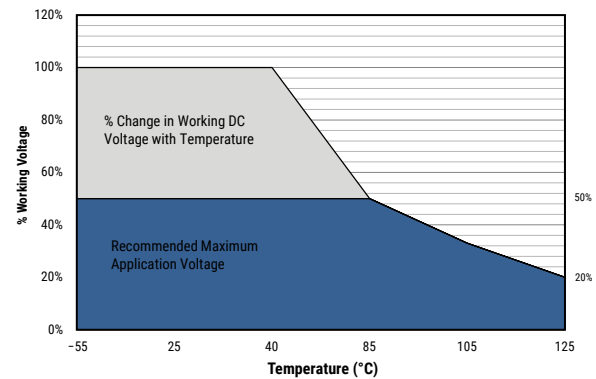
The ESR value may increase up to 1.5 x Initial Limit post mounting

The DCL value may increase up to 2.0 x Initial Limit post mounting

Higher voltage ratings and tighter tolerance product including ESR may be substituted within the same size at KEMET's option. Voltage substitution will be marked with the higher voltage rating. Substitutions can include better than series.

## Recommended Voltage Derating Guidelines

-55°C to 40°C		
% Change in Working DC Voltage with Temperature	100% of V <sub>R</sub>	V <sub>R</sub>
Recommended Maximum Application Voltage	50% of V <sub>R</sub>	V <sub>R</sub>
40°C to 85°C		
% Change in Working DC Voltage with Temperature	50% of V <sub>R</sub>	V <sub>R</sub>
Recommended Maximum Application Voltage	50% of V <sub>R</sub>	V <sub>R</sub>
85°C to 125°C		
% Change in Working DC Voltage with Temperature	20% of V <sub>R</sub>	V <sub>R</sub>
Recommended Maximum Application Voltage	20% of V <sub>R</sub>	V <sub>R</sub>



## Ripple Current/Ripple Voltage

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.
2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

Temperature Compensation Multipliers for Maximum Ripple Current		
T ≤ 25°C	T ≤ 40°C	T ≤ 85°C
1.00	0.90	0.40

T = Environmental Temperature

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

KEMET Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts at 25°C w/+20°C Rise
A	3216-18	75
B	3528-21	85
T	3528-12	70

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

$$I(max) = \sqrt{P_{max}/R}$$

$$E(max) = Z \sqrt{P_{max}/R}$$

I = rms ripple current (amperes)

E = rms ripple voltage (volts)

P max = maximum power dissipation (watts)

R = ESR at specified frequency (ohms)

Z = Impedance at specified frequency (ohms)

## Reverse Voltage

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the table. The capacitors should not be operated continuously in reverse mode, even within these limits.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
40°C	5% of Rated Voltage
85°C	1% of Rated Voltage

**Table 2 – Land Dimensions/Courtyard**

KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)					Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)					
		Case	EIA	W	L	S	V1	V2	W	L	S	V1	V2	W	L	S	V1
A	3216-18		1.35	2.20	0.62	6.02	2.80	1.23	1.80	0.82	4.92	2.30	1.13	1.42	0.98	4.06	2.04
B	3528-21		2.35	2.21	0.92	6.32	4.00	2.23	1.80	1.12	5.22	3.50	2.13	1.42	1.28	4.36	3.24
T	3528-12		2.35	2.20	0.92	6.32	4.00	2.23	1.80	1.12	5.22	3.50	2.13	1.42	1.28	4.36	3.24

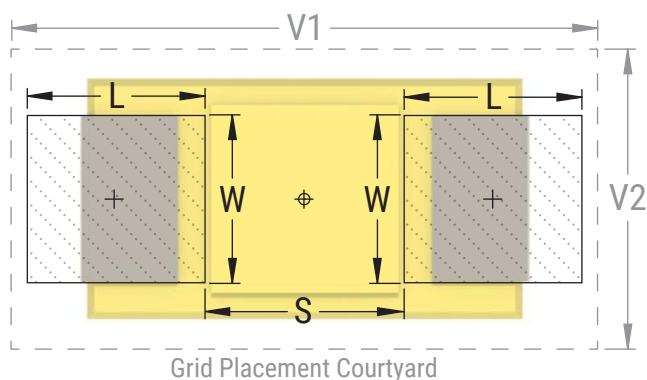
**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

**Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC standard 7351 (IPC-7351).

<sup>1</sup> Height of these chips may create problems in wave soldering.

<sup>2</sup> Land pattern geometry is too small for silkscreen outline.





## Soldering Process

KEMET’s families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET’s recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J–STD–020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343–43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. “Wiping” the edges of a chip and heating the top surface is not recommended.

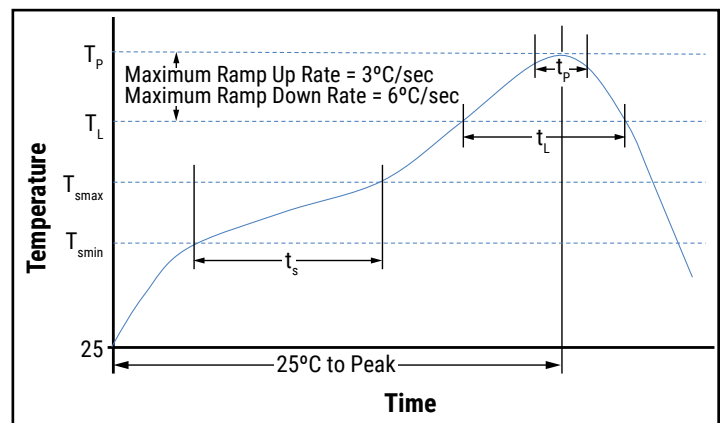
During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
<b>Preheat/Soak</b>		
Temperature Minimum ( $T_{smin}$ )	100°C	150°C
Temperature Maximum ( $T_{smax}$ )	150°C	200°C
Time ( $t_s$ ) from $T_{smin}$ to $T_{smax}$	60 – 120 seconds	60 – 120 seconds
Ramp-up Rate ( $T_L$ to $T_P$ )	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature ( $T_L$ )	183°C	217°C
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds
Peak Temperature ( $T_P$ )	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature ( $t_p$ )	20 seconds maximum	30 seconds maximum
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

\*Case Size D, E, P, Y, and X

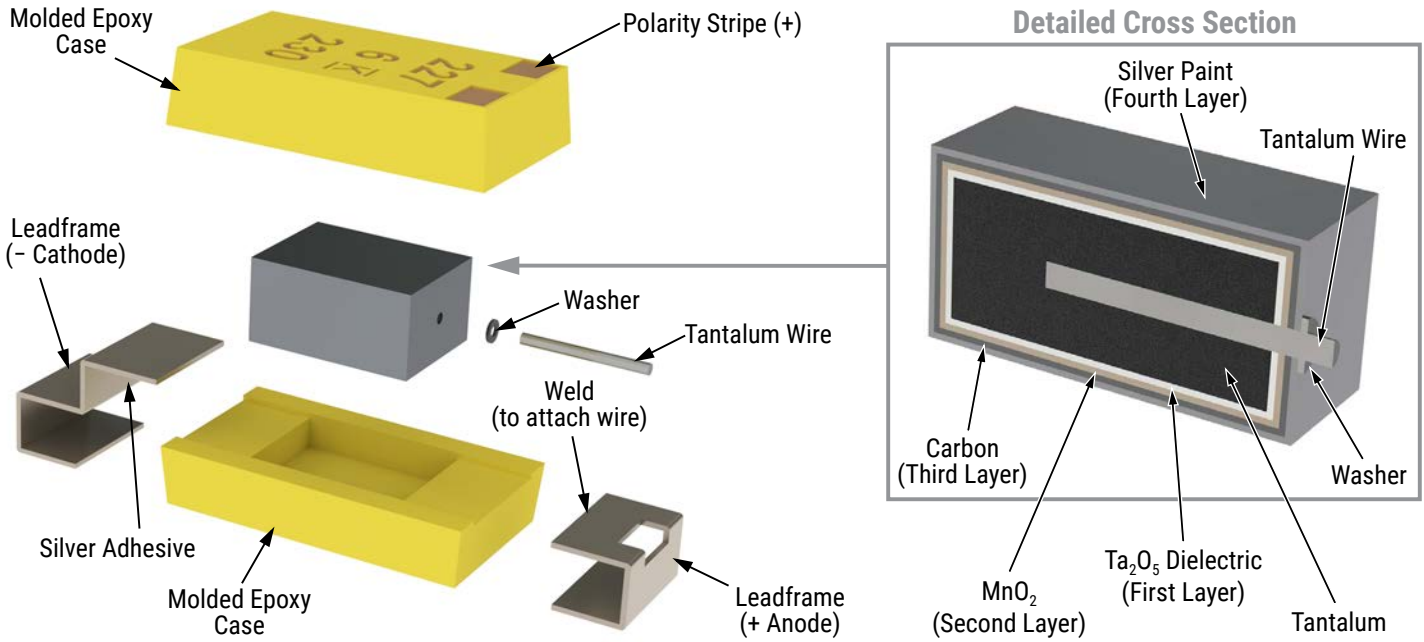
\*\*Case Size A, B, C, H, I, K, M, R, S, T, U, V, W, and Z



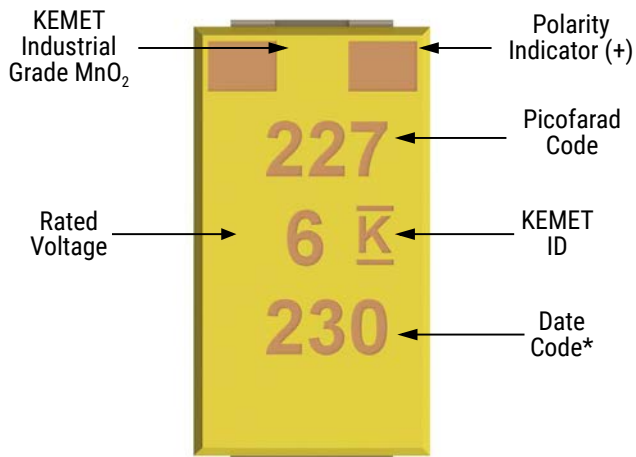
## Storage

Tantalum chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 60% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulphur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within three years of receipt.

## Construction



## Capacitor Marking

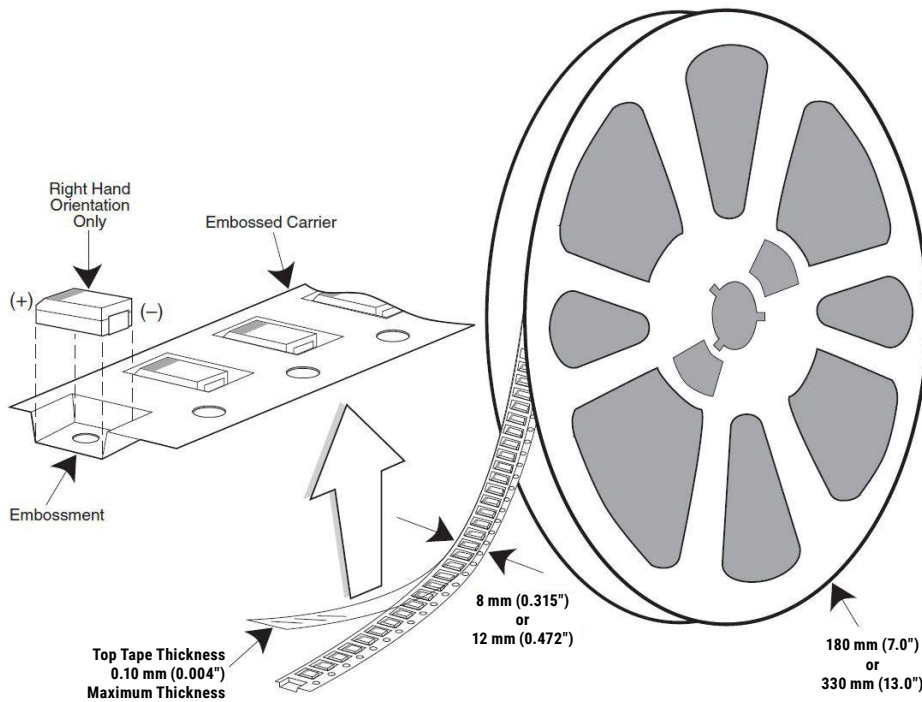


\* 230 = 30<sup>th</sup> week of 2012

Date Code *	
1 <sup>st</sup> digit = Last number of Year	2 = 2012 3 = 2013 4 = 2014 5 = 2015 6 = 2016 7 = 2017
2 <sup>nd</sup> and 3 <sup>rd</sup> digit = Week of the Year	01 = 1 <sup>st</sup> week of the Year to 52 = 52 <sup>nd</sup> week of the Year

## Tape & Reel Packaging Information

KEMET’s molded chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481: Embossed Carrier Taping of Surface Mount Components for Automatic Handling*. This packaging system is compatible with all tape-fed automatic pick-and-place systems.

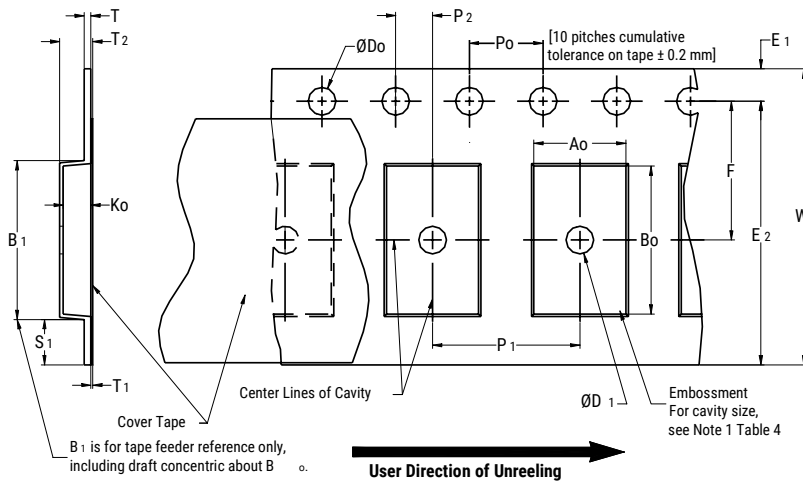


**Table 3 – Packaging Quantity**

Case Code		Tape Width (mm)	7" Reel*	13" Reel*
KEMET	EIA			
S	3216-12	8	2,500	10,000
T	3528-12	8	2,500	10,000
M	3528-15	8	2,000	8,000
U	6032-15	12	1,000	5,000
L	6032-19	12	1,000	3,000
W	7343-15	12	1,000	3,000
Z	7343-17	12	1,000	3,000
V	7343-20	12	1,000	3,000
A	3216-18	8	2,000	9,000
B	3528-21	8	2,000	8,000
C	6032-28	12	500	3,000
D	7343-31	12	500	2,500
Q	7343-12	12	1,000	3,000
Y	7343-40	12	500	2,000
X	7343-43	12	500	2,000
E/T428P	7360-38	12	500	2,000
H	7360-20	12	1,000	2,500

\* No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.

**Figure 1 – Embossed (Plastic) Carrier Tape Dimensions**



**Table 4 – Embossed (Plastic) Carrier Tape Dimensions**

Metric will govern

Constant Dimensions – Millimeters (Inches)											
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum		
8 mm	1.5+0.10/-0.0 (0.059+0.004/-0.0)	1.0 (0.039)	1.75±0.10 (0.069±0.004)	4.0±0.10 (0.157±0.004)	2.0±0.05 (0.079±0.002)	25.0 (0.984)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)		
12 mm		1.5 (0.059)								2.0±0.1 (0.079±0.059)	30 (1.181)
16 mm											

Variable Dimensions – Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5±0.05 (0.138±0.002)	2.0±0.05 or 4.0±0.10 (0.079±0.002 or 0.157±0.004)	2.5 (0.098)	8.3 (0.327)	Note 5	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5±0.05 (0.217±0.002)	2.0±0.05 (0.079±0.002) or 4.0±0.10 (0.157±0.004) or 8.0±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)		
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5±0.10 (0.295±0.004)	4.0±0.10 (0.157±0.004) to 12.0±0.10 (0.472±0.004)	8.0 (0.315)	16.3 (0.642)		

- The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- The tape, with or without components, shall pass around R without damage (see Figure 4).
- If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481-D, paragraph 4.3, section b).
- B<sub>1</sub> dimension is a reference dimension for tape feeder clearance only.
- The cavity defined by A<sub>0</sub>, B<sub>0</sub> and K<sub>0</sub> shall surround the component with sufficient clearance that:
  - the component does not protrude above the top surface of the carrier tape.
  - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).
  - lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).
  - see Addendum in EIA Standard 481-D for standards relating to more precise taping requirements.

## Packaging Information Performance Notes

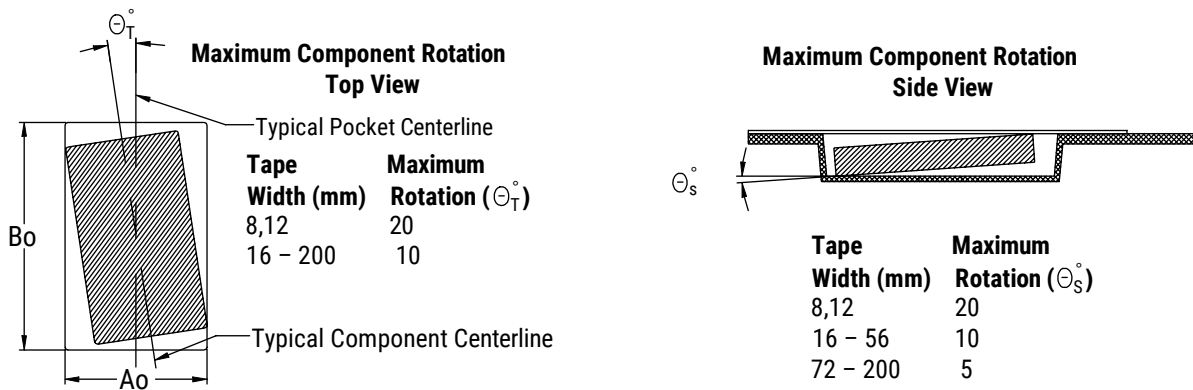
- Cover Tape Break Force:** 1.0 Kg minimum.
- Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

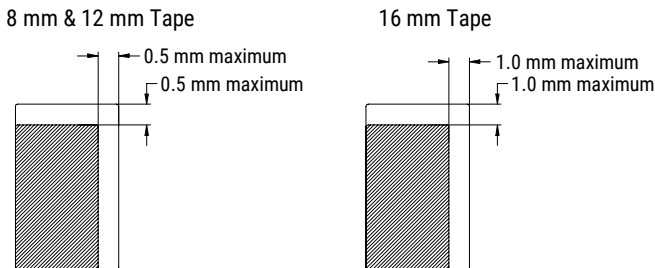
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

- Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

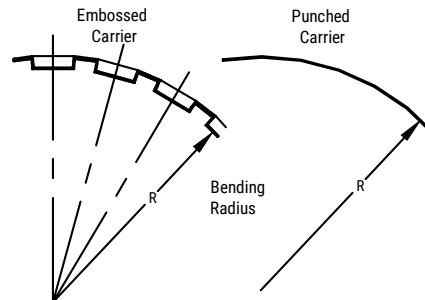
## Figure 2 – Maximum Component Rotation



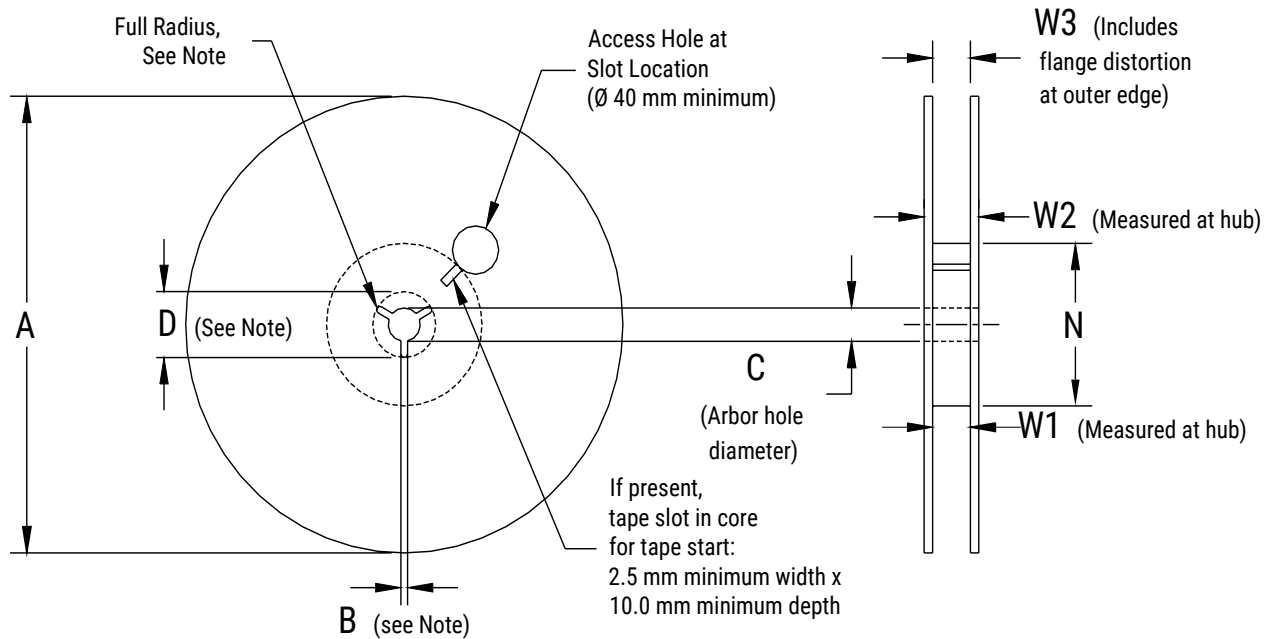
## Figure 3 – Maximum Lateral Movement



## Figure 4 – Bending Radius



**Figure 5 – Reel Dimensions**



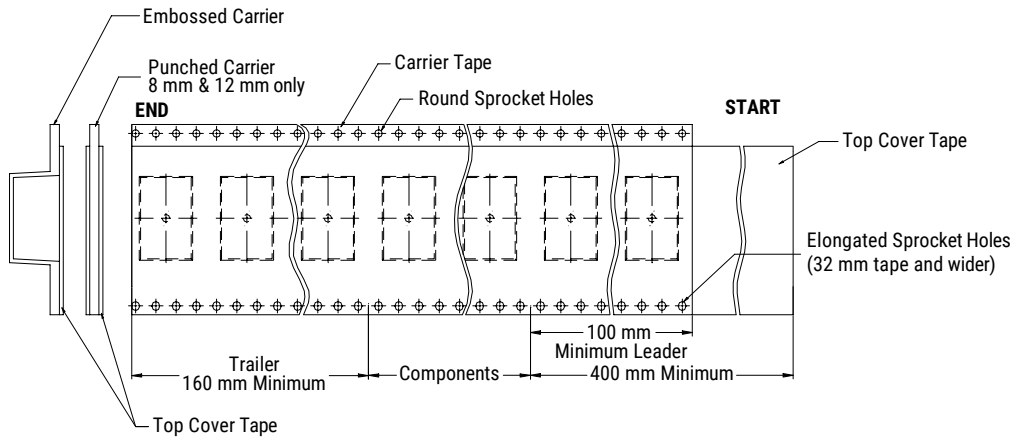
Note: Drive spokes optional; if used, dimensions B and D shall apply.

**Table 5 – Reel Dimensions**

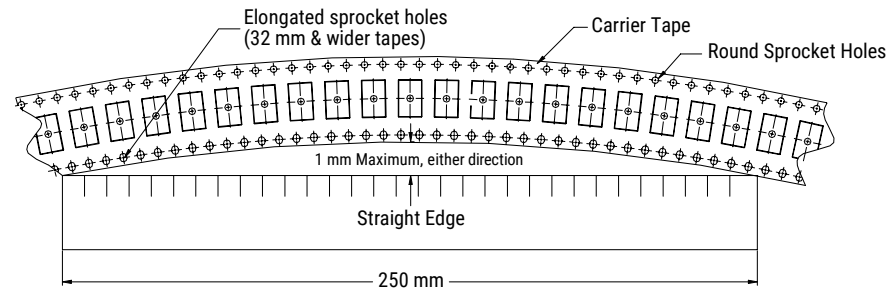
Metric will govern

Constant Dimensions – Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
8 mm	178±0.20 (7.008±0.008) or 330±0.20 (13.000±0.008)	1.5 (0.059)	13.0+0.5/-0.2 (0.521+0.02/-0.008)	20.2 (0.795)
12 mm				
16 mm				
Variable Dimensions – Millimeters (Inches)				
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>
8 mm	50 (1.969)	8.4+1.5/-0.0 (0.331+0.059/-0.0)	14.4 (0.567)	Shall accommodate tape width without interference
12 mm		12.4+2.0/-0.0 (0.488+0.078/-0.0)	18.4 (0.724)	
16 mm		16.4+2.0/-0.0 (0.646+0.078/-0.0)	22.4 (0.882)	

**Figure 6 – Tape Leader & Trailer Dimensions**



**Figure 7 – Maximum Camber**



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